

Title (en)  
Metal-made seamless pipe and process for production thereof

Title (de)  
Nahhtloses Metalrohr und Verfahren zu seiner Herstellung

Title (fr)  
Tube sans soudure en métal et procédé pour sa fabrication

Publication  
**EP 1195214 A1 20020410 (EN)**

Application  
**EP 01308458 A 20011003**

Priority  
• JP 0006876 W 20001003  
• JP 2001217592 A 20010718

Abstract (en)  
A metal-made seamless pipe contains, as a main component, at least one kind of metal selected from the group consisting of metals each having a melting point of 1,600 DEG C or more. The metal-made seamless pipe has a porosity of 0.3 to 25% when the porosity is defined as a proportion of the open pores not perforating in the thickness direction of the pipe, present at the outer surface of the pipe, to the total area (100%) of the outer surface of the pipe; and a process for producing such a metal-made seamless pipe. The metal-made seamless pipe is low in processability but can be produced in a small thickness and a small inner diameter, is superior in mechanical strengths and gastightness, and can be suitably used as a sealing member of a translucent vessel of a high-pressure discharge lamp.

IPC 1-7  
**B22F 3/11**; **B22F 5/10**; **H01J 61/36**

IPC 8 full level  
**H01J 5/36** (2006.01); **B22F 3/11** (2006.01); **B22F 5/10** (2006.01); **C04B 38/00** (2006.01); **C22C 32/00** (2006.01); **H01J 61/36** (2006.01)

CPC (source: EP)  
**B22F 3/1103** (2013.01); **B22F 5/106** (2013.01); **C22C 32/0031** (2013.01); **H01J 61/366** (2013.01)

Citation (search report)  
• [XY] US 3626744 A 19711214 - SORGENFREI FREDERICK J  
• [XY] US 5910007 A 19990608 - SHIMODAIRA KENICHI [JP], et al  
• [YD] EP 0982278 A1 20000301 - NGK INSULATORS LTD [JP]  
• [Y] PATENT ABSTRACTS OF JAPAN vol. 007, no. 001 (M - 183) 6 January 1983 (1983-01-06)

Cited by  
CN104736274A; EP1686614A3; US9950368B2; US7602115B2; US7453212B2

Designated contracting state (EPC)  
BE DE FR GB NL

DOCDB simple family (publication)  
**EP 1195214 A1 20020410**; **EP 1195214 B1 20041222**; CN 1151539 C 20040526; CN 1347135 A 20020501; CZ 20013545 A3 20020515; CZ 296639 B6 20060517; DE 60107914 D1 20050127; DE 60107914 T2 20051215

DOCDB simple family (application)  
**EP 01308458 A 20011003**; CN 01135350 A 20010930; CZ 20013545 A 20011002; DE 60107914 T 20011003